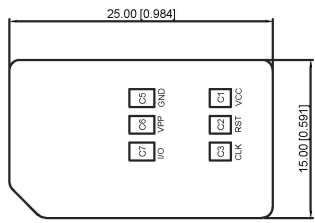
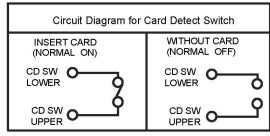
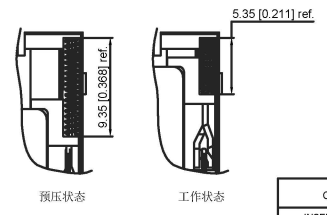


NOTES:
 1) MATERIAL:
 HOUSING: LCP UL 94V-0
 TERMINAL: COPPER ALLOY ,T=0.15
 SHELL: SUS,T=0.15
 MYLAR: POLYESTER
 2) FINISH :
 TERMINAL: GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATING ON SOLDER TAILS, WITH
 ENTIRE CONTACT UNDERPLATED 50u"Min, NICKEL
 SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL ,
 GOLD FLASH PLATED ON SOLDER TAILS
 3) INFRARED REFLOW SOLDERING: 10sec. Min. at 260₀°



2FF SIM CARD

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	8	COPPER ALLOY	
①	Housing	1	LCP UL 94V-0	BLACK

广东星坤科技股份有限公司

MARK	DESCRIPTION	DATE	REVISED	APPROVED
生				
效				
日期				

UNSPECIFIED TOLERANCES	ANGULAR	±5°
	L ≤ 4	±0.2
	4 < L ≤ 16	±0.3
	16 < L ≤ 63	±0.4
	L > 63	±0.5

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	SIM CARD CONN
CHKD	DATE	UNIT: mm/in	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.: XKSIM-115
XKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT 1.0g
			SHEET 1/1
			REVISION A0